



**LP-ISM035**

**Features**

- Very small size of 0805
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



**Product Dimensions (mm)**

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-ISM035	2.20	1.50	0.75	0.10	0.20

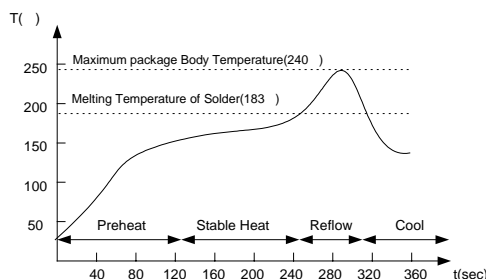
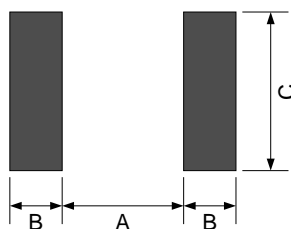


**Electrical Characteristics**

Part number	I <sub>H</sub> (A)	I <sub>T</sub> (A)	V <sub>max</sub> (V)	I <sub>max</sub> (A)	T <sub>trip</sub> Current(A) Time(S)	Pd <sub>typ</sub> (W)	R <sub>min</sub> ( )	R <sub>1max</sub> ( )
LP-ISM035	0.35	0.75	6.00	40.0	8.00 0.10	0.5	0.25	1.20

I<sub>H</sub>=Hold current: maximum current at which the device will not trip at 25 °C still air.  
 I<sub>T</sub>=Trip current: minimum current at which the device will always trip at 25 °C still air.  
 V<sub>max</sub>=Maximum voltage device can withstand without damage at rated current.  
 I<sub>max</sub>=Maximum fault current device can withstand without damage at rated voltage.  
 T<sub>trip</sub>=Maximum time to trip(s) at assigned current.  
 R<sub>min</sub>=Minimum device resistance at 25 °C prior to tripping.  
 R<sub>1max</sub>=Maximum device resistance measured in the nontripped state 1 hour post reflow.

**Solder Reflow Recommendations**



**Solder Pad Layouts**

Part number	A (mm)	B (mm)	C (mm)
LP-ISM035	1.80	1.00	1.80

\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

\* Devices can be cleaned using standard industry methods and solvents.

**Notes:**

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.